IEEE to Hold International Integrated Reliability Workshop in October 2008

www.iirw.org

The 2008 IEEE International Integrated Reliability Workshop (IIRW) will be held on October 12–16 at Stanford Sierra Camp, near South Lake Tahoe, California.

The workshop focus is on achieving electronic device reliability through optimization of fabrication, design, testing, characterization, and simulation as well as on identification of the underlying physical mechanisms and defects responsible for reliability problems. The IIRW consistently attracts an outstanding international group of engineers and scientists who work on a wide range of issues associated with device scaling, integration of

novel materials, new test methodologies, and reliability modeling.

This year's meeting will offer introductory and advanced tutorials and technical presentations on innovative reliability topics, including problems with high-k and nitrided SiO₂ gate devices, Cu interconnects, low-k dielectrics, reliability modeling and simulations, SiGe and strained Si, and emerging memory technologies. A partial list of invited tutorial speakers and topics include **Tibor Grasser**, Technical University of Vienna, "The Negative Bias Temperature Instability (NBTI)"; **Chadwin Young**, SEMATECH, "Measurement

Issues for High-*k* Technology and NBTI"; and Wilfried Haensch, IBM, "Reliability of 'Future' Devices." The presentations will be opened by keynote speaker Dakshi Dakshinamoorthy, vice president of quality and reliability at Freescale Semiconductor.

More information can be found at the IIRW Web site at www.iirw.org or by contacting the general chair, Pat Lenahan, Penn State, 814-863-4630, PMLESM@ engr.psu.edu or the technical program chair Guoqiao Tao, NXP Semiconductor, tel. 31-24-35-345-49, or e-mail Guoqiao. tao@nxp.com.

2nd International Advanced Materials Summit to Be Held in Tianjin

www.chemevent.com.cn/IAMS08 en

As the prices of energy and raw materials continue to rise, advanced materials will contribute to the development of sustainable solutions. In China, the advanced materials industry is providing technology support and function assurance to the 2008 Olympic Games and to key projects such as large aircraft and manned space flight. The industry is in a position of significant development opportunities.

Following the debut of the Bo'ao International Advanced Materials Forum (held on March 27–29, 2007 in Bo'ao, Hainan Province, China), the 2nd International Advanced Materials Summit will be held in Tianjin, China from October 30 to November 1, 2008. Tianjin is considered to be the base of the petrochemical and advanced modern manufacturing industries.

In keeping with the theme of "Opportunity and Responsibility," the summit will provide an environment to discuss how to grasp opportunity and implement responsibility in the advanced materials industry under the circumstances of global economic adjustment.

With the aim of convening a high-end leading conference, the summit presentation adopts two forms: plenary speech and panel discussion. The following three technology sessions are arranged to probe industry frontier technology: Composite Materials and Aerospace Application, Chemical Materials and Lightweight Automobile, and Membrane Materials and Environment and Water Resources. Experts from multinational petrochemical companies such as CNPC, Sinopec, CNOOC, BASF, Bayer, Celanese, DOW,

DSM, DuPont, Evonik Degussa, Lanxess, and SABIC have already confirmed their participation, as well as those from the Chinese Academy of Sciences and Technology and other international research institutions.

The conference is co-organized by Tianjin Municipal People's Government, China National Chemical Corporation (ChemChina), the Society for Chemical Engineering and Biotechnology (DECHEMA e.V.), and Morgan Stanley, and is executed by China National Chemical Information Center (CNCIC) and the Administrative Committee of Tianjin Binhai New Area. The summit is endorsed by the Materials Research Society.

